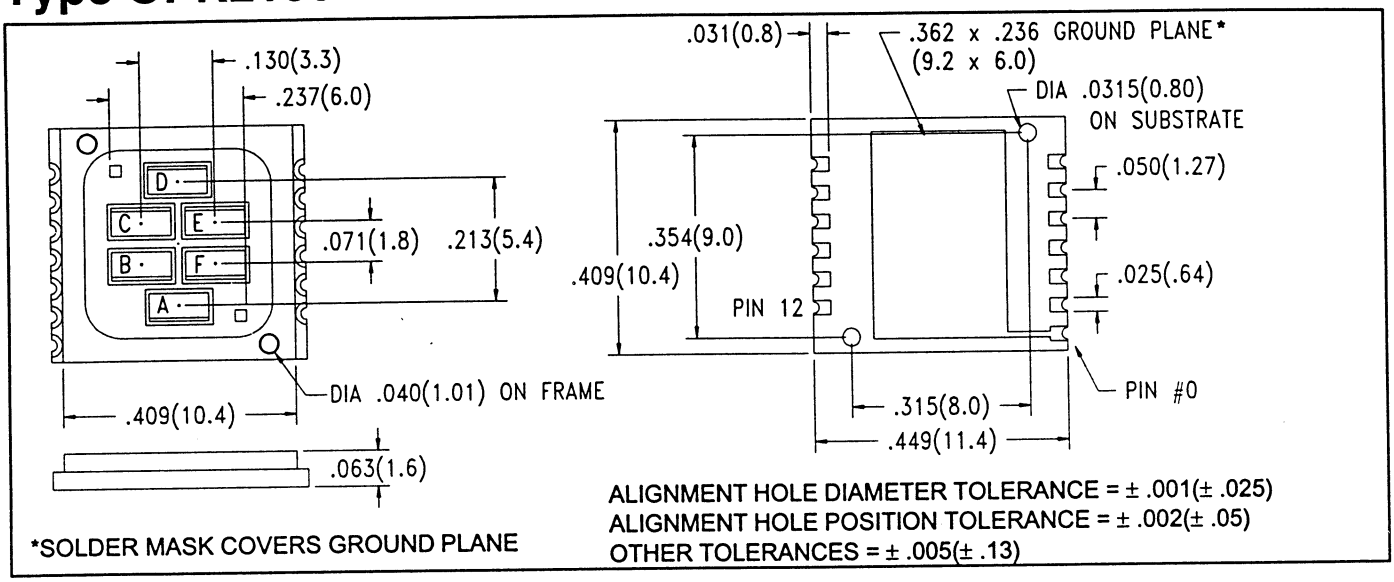
Six Element SMD Photodiode Array
Type OPR2100



Features

- Surface Mountable
- Closely Matched Responsivity
- High Temperature Operation

Description

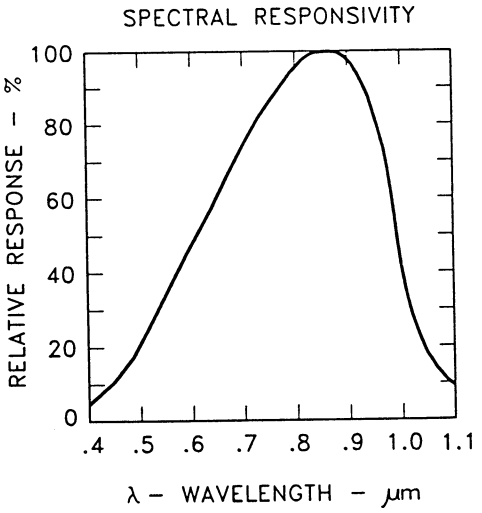
Enclosed in a compact polyimide chip carrier, this six element photodiode has been specifically designed to meet the needs of motor encoder applications. Six individual chips are mounted on isolated cathode contacts to allow external connection in any desired configuration. The custom opaque package material shields the photodiodes from stray light and can withstand multiple exposures to the most demanding soldering conditions. The wrap around solder pads are gold plated for exceptional storage and wetting characteristics.

Absolute Maximum Ratings (T_A = 25° C unless otherwise noted)

Storage and Operating Temperature ..... -55° C to +125° C
Reverse Breakdown Voltage ..... 50 V Min.
Solder Temperature (Vapor Phase Reflow for 30 sec.) ..... 235° C

PIN OUT:

PIN #0.	GROUND PLANE
1.	CATHODE A
2.	CATHODE B
3.	ANODE B
4.	ANODE C
5.	CATHODE C
6.	CATHODE D
7.	ANODE D
8.	CATHODE E
9.	ANODE E
10.	ANODE F
11.	CATHODE F
12.	ANODE A



HYBRID ASSEMBLIES

Electrical Characteristics (T_A = 25° C unless otherwise noted)

SYMBOL	PARAMETERS	MIN	TYP	MAX	UNITS	TEST CONDITIONS
R_λ	Responsivity	0.45			A/W	Φ_e= 10 μW, λ = 890 nm, V = 0 V
$V_{(BR)R}$	Reverse Breakdown Voltage	50			V	I_R = 100 μA
I_D	Reverse Dark Current			10	nA	V_R = 10 V
C_T	Capacitance		10		pf	V_R = 10 V
L x W	Active Area (per diode)		2.9		mm^2	(1.1 mm x 2.6 mm)